

### 華泰電子股份有限公司

Orient Semiconductor Electronics, Ltd.

(股票代號:2329)

### 2023年Q3法人說明會 INVESTOR CONFERENCE

24 NOV,2023



### Summary

- Part 1 Company Profile
- Part 2 Manufacture Service & Product
- Part 3 2023 Q3 Financial Performance
- Part 4 Competitive Advantage
- Part 5 Q&A





### **Company Profile**





### **Company History**



>> 資本額 Capital : US\$ 233M (NTD7.35B)

Common Stock : US\$ 176M (NTD5.55B) Preferred C Stock : US\$ 57M (NTD1.80B) 2023

**52th Anniversary Celebration** 

2015 & 2020

**Strategic Partnership Announcement** 

2014

1st 16D microSD in the world

2005

**IC Business Transformation into Memory related** 

2000

**HQ Building Officially Opened** 

Apr, 1994

IPO in Taiwan Stock Exchange (TSE: 2329)

1971 Established

Founder: Dr. Eugene C. Y. Duh

Headquarters: Kaohsiung, Taiwan



### **Factory**



Headquarters (Flash Memory) (750,000 sq. ft.)

- >> 6 Production buildings in NTIP
- >> Headcount : around 5,100



Facility 2 (59,223 sq. ft.)



LIC (256,200 sq. ft.)



Facility 1 (146,475 sq ft.)



Facility 3 (158,638 sq. ft.)



Facility 5 (190,000 sq. ft.)



### Organization

Chairman **Tony Tung President** C. J. Tu

Testing Group
Terry Lin

- Memory IC Testing Service
- Logic IC Testing Service

Semiconductor Group M. L. Tsai

- Memory IC Packaging Service
- Logic IC Packaging Service

EMS Group Major Lee

EMS Service



# Manufacture Service & Product





### **Total Solution**



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### **Total Solution**

#### >>> Electronics Manufacturing Service



**Product Design** from Customer



JDM, DFM, DFT



NPI & Quick Turn Prototyping



Material Procurement





Repair and Upgrade



Distribution Support



System Integration



**Box Build** 



Functionality & Reliability Testing



### **Product Application**



**Memory** 

Consumer Electronics

Industrial

Automotive

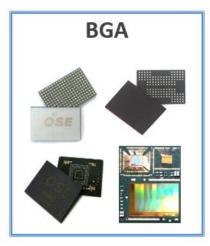
Aerospace

Communication







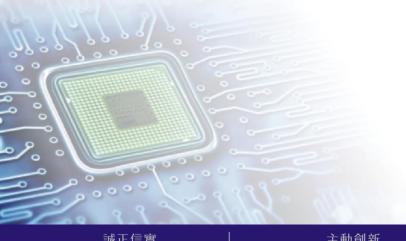




<sup>\*</sup>Includes Wire Bond Type, Flip Chip Type, SiP, etc



# 2023 Q3 Financial Performance



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# CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME (QoQ)

(Thousands of NTD)	Q3/2023	%	Q2/2023	%	Variance
Net revenue	4,702,077	100.00%	3,998,666	100.00%	17.59%
Gross profit	1,063,011	22.61%	740,953	18.53%	43.47%
Operating income	708,932	15.08%	418,704	10.47%	69.32%
Income before tax	793,743	16.88%	571,862	14.30%	38.80%
Income tax(expense)	(207,042)	(4.40%)	(57,504)	(1.44%)	260.05%
Non controlling interests	-	-	-	-	-
Net Income	586,701	12.48%	514,358	12.86%	14.06%
Basic EPS (in NTD)	0.82	-	0.72	-	-
EBITDA	1,043,304	22.19%	843,644	21.10%	23.67%

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# CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME (YoY)

(Thousands of NTD)	Q3/2023	%	Q3/2022	%	Variance
Net revenue	4,702,777	100.00%	3,808,937	100.00%	23.45%
Gross profit	1,063,011	22.61%	611,548	16.06%	73.82%
<b>Operating income (loss)</b>	708,932	15.08%	352,296	9.25%	101.23%
Income (loss) before tax	793,743	16.88%	512,819	13.46%	54.78%
Income tax (expense) gains	(207,042)	(4.40%)	(79,978)	(2.10%)	158.87%
Non controlling interests	-	-	-	-	-
Net Income	586,701	12.48%	432,841	11.36%	35.55%
Basic EPS (in NTD)	0.82	-	0.65	-	-
EBITDA	1,043,304	22.19%	794,051	20.85%	31.39%

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### CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME (Accumulated, YoY)

(Thousands of NTD)	Q1~Q3/2023	%	Q1~Q3/2022	%	Variance
Net revenue	11,954,154	100.00%	11,936,056	100.00%	0.15%
Gross profit	2,125,371	17.78%	2,015,860	16.89%	5.43%
Operating income (loss)	1,228,640	10.28%	1,167,827	9.78%	5.21%
Income (loss) before tax	1,463,354	12.24%	1,489,519	12.48%	(1.76%)
Income tax (expense) gains	(182,574)	(1.53%)	(268,931)	(2.25%)	(32.11%)
Non controlling interests	-	-	-	-	-
Net Income	1,280,780	10.71%	1,220,588	10.23%	4.93%
Basic EPS (in NTD)	1.80	-	1.78	-	-
EBITDA	2,262,008	18.92%	2,376,537	19.91%	(4.82%)

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### **Key Items & Index of Balance Sheet**

(Thousands of NTD)	Q3/2023	Q2/2023	Variance
Cash and cash equivalents	4,056,506	3,820,624	6.17%
Financial assets measured at amortized cost	-	-	-
Financial assets-Noncurrent & Investments-equity method	1,671,283	1,453,450	14.99%
Property, plant, and equipment	5,116,203	5,184,714	(1.32%)
Total assets	18,455,649	17,817,892	3.58%
Short-term loans & Short-term notes payable	-	-	_
Long-Term Liabilities-Current Portion	29,648	11,618	155.19%
Long-term loans	1,149,314	1,137,344	1.05%
Total liabilities	7,798,311	7,897,825	(1.26%)
Total stockholders' equity	10,657,338	9,920,067	7.43%
Quarterly EBITDA	1,043,304	843,644	23.67%
Index			
Debt ratio	42.25%	44.33%	
Accounts receivable turnover days(Q3)	78Days	76Days	
Inventory turnover days(Q3)	41Days	45Days	

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### **Key Items & Index of Balance Sheet**

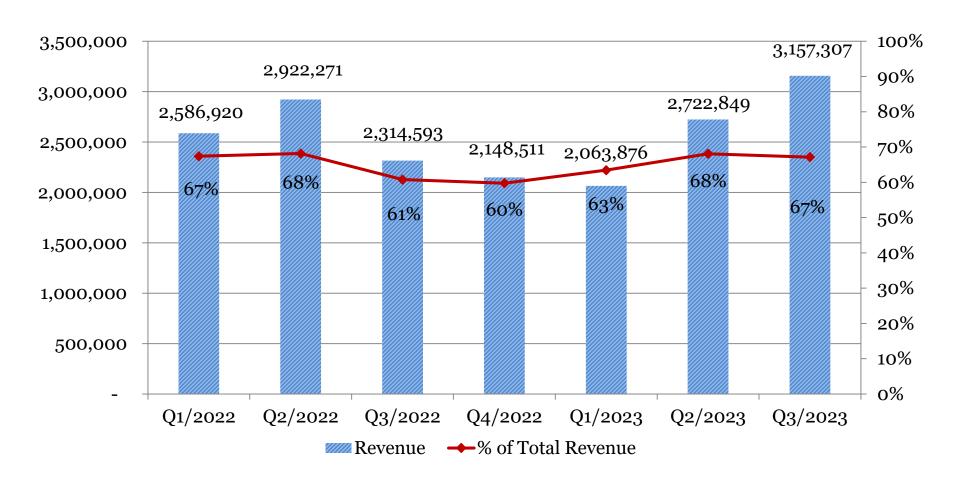
(Thousands of NTD)	Q3/2023	Q3/2022	Variance
Cash and cash equivalents	4,056,506	3,489,963	16.23%
Financial assets measured at amortized cost	-	-	-
Financial assets-Noncurrent & Investments-equity method	1,671,283	812,032	105.81%
Property, plant, and equipment	5,116,203	5,298,908	(3.45%)
Total assets	18,455,649	16,534,366	11.62%
Short-term loans & Short-term notes payable	-	400,000	(100.00%)
Long-Term Liabilities-Current Portion	29,648	-	-
Long-term loans	1,149,314	743,962	54.49%
Total liabilities	7,798,311	7,198,885	8.33%
Total stockholders' equity	10,657,338	9,335,481	14.16%
Quarterly EBITDA	1,043,304	794,051	31.39%
Index			
Debt ratio	42.25%	43.54%	
Accounts receivable turnover days(Q1~Q3)	84Days	77Days	
Inventory turnover days(Q1~Q3)	47Days	52Days	

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### **IC Packaging and Testing Services**

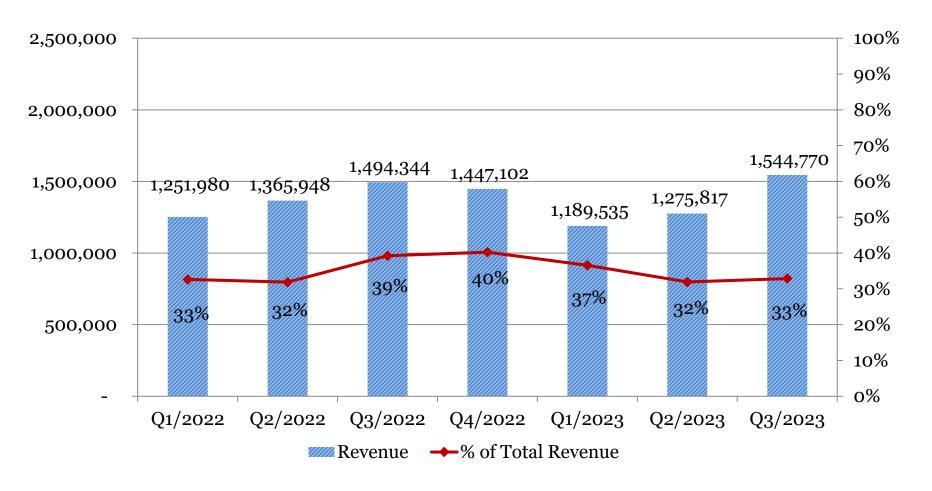
(Thousands of NTD)





### **Electronics Manufacturing Services**

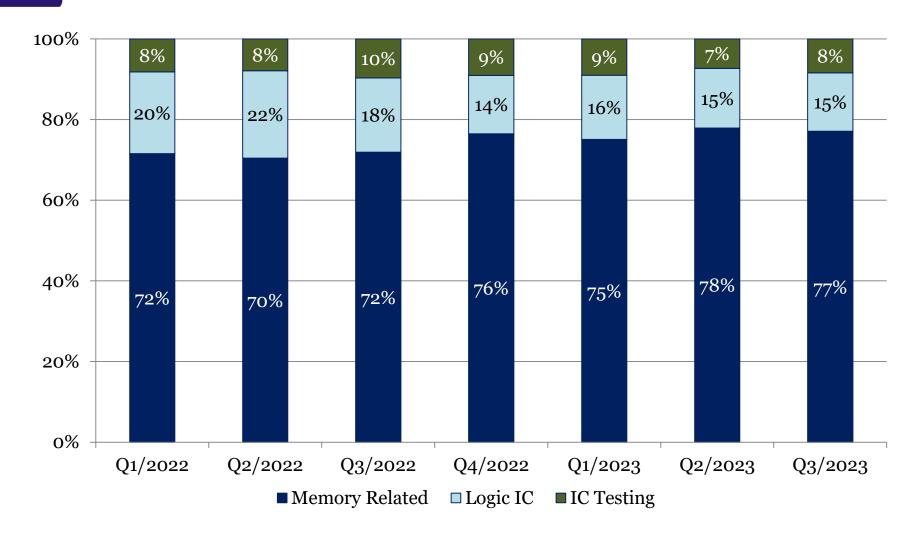
(Thousands of NTD)





### **Semiconductor Group**

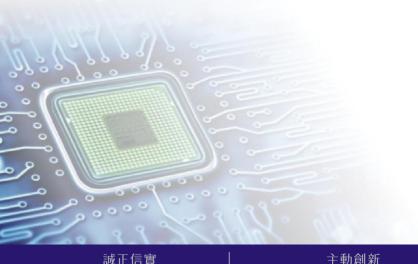
-Percentage of revenue by product application

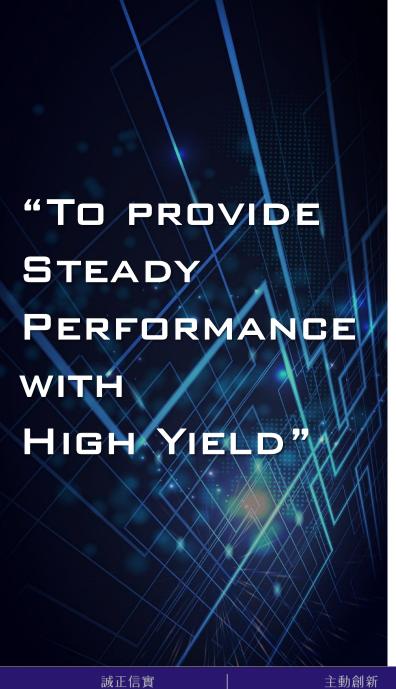


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## Competitive Advantage







- Focus on Memory Market for 20 years.
- Efficient Manufacture Platform for Memory.



- Advanced Process Capability
  - 25um wafer thickness
  - 16 Layers Die Stacking for microSD/BGA/SD
  - 1ST 1TB microSD announced to market



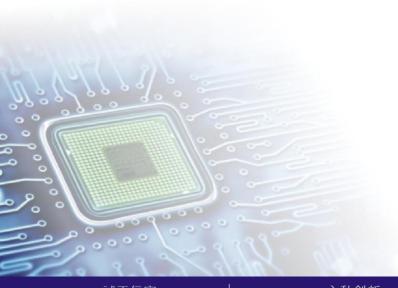
- Highly Systematized Production Environment
- MES Automation System



- One-Stop Service
- High Degree of Flexibility on capacity allocation



### Q&A



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### Disclaimer

The presentation and the relevant information mentioned in this material have been compiled from both internal and external resources.

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The forward looking statements expressed in this material reflect the Company's current view about the future as of today. The Company is not responsible for any updates if there are any changes in the future.